





P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)} max	I _D T _A = +25°C
-50V	10Ω @ V _{GS} = -5V	-130mA

Description

This MOSFET has been designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

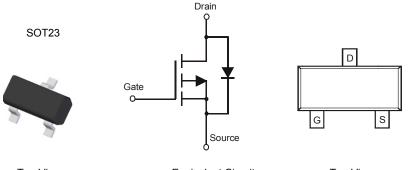
- · General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish (Lead Free Plating) Solderable per MIL-STD-202, Method 208 @3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)



Top View Equivalent Circuit Top View

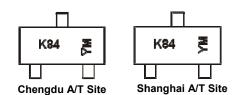
Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BSS84-7-F	Commercial	SOT23	3000/Tape & Reel
BSS84Q-7-F	Automotive	SOT23	3000/Tape & Reel
BSS84-13-F	Commercial	SOT23	10000/Tape & Reel
BSS84Q-13-F	Automotive	SOT23	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.dioides.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



K84 = Product Type Marking Code

 $\begin{array}{l} \text{YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)} \\ \overline{\text{YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)} \\ \end{array}$

Y or \overline{Y} = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004		2011	2012	2013	2014	2015	2016	2017
Code	J	K	L	М	N	Р	R		Υ	Z	Α	В	С	D	Е
Month	Jan	Fe	b I	Mar	Apr	May	Ju	n	Jul	Aug	Sep	Oc	t I	Nov	Dec
Code	1	2		3	4	5	6		7	8	9	0		N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	-50	V
Drain-Gate Voltage $R_{GS} \le 20 K\Omega$		V_{DGR}	-50	V
Gate-Source Voltage	Continuous	V_{GSS}	±20	V
Drain Current (Note 5)	Continuous	I _D	-130	mA
Pulsed Drain Current		I _{DM}	-1.2	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_D	300	mW
Thermal Resistance, Junction to Ambient	$R_{ hetaJA}$	417	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV _{DSS}	-50	1	_	V	$V_{GS} = 0V, I_D = -250\mu A$
				-1	μA	$V_{DS} = -50V$, $V_{GS} = 0V$, $T_{J} = +25$ °C
Zero Gate Voltage Drain Current	I_{DSS}	_	_	-2	μΑ	$V_{DS} = -50V$, $V_{GS} = 0V$, $T_{J} = +125$ °C
			_	-100	nA	$V_{DS} = -25V$, $V_{GS} = 0V$, $T_{J} = +25$ °C
Gate-Body Leakage	I _{GSS}		1	±10	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.8	-	-2.0	V	$V_{DS} = V_{GS}$, $I_D = -1mA$
Static Drain-Source On-Resistance	R _{DS} (ON)		1	10	Ω	$V_{GS} = -5V$, $I_D = -0.100A$
Forward Transconductance	9 FS	0.05	_	_	S	$V_{DS} = -25V$, $I_{D} = -0.1A$
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C _{iss}		-	45	pF	
Output Capacitance	Coss		1	25	pF	$V_{DS} = -25V$, $V_{GS} = 0V$, $f = 1.0MHz$
Reverse Transfer Capacitance	Crss			12	pF	
SWITCHING CHARACTERISTICS (Note 7)			•			
Turn-On Delay Time	t _{D(ON)}		10	_	ns	$V_{DD} = -30V$, $I_D = -0.27A$,
Turn-Off Delay Time	t _{D(OFF)}	_	18	_	ns	R_{GEN} = 50 Ω , V_{GS} = -10 V

Notes:

- 5. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Guaranteed by design. Not subject to production testing



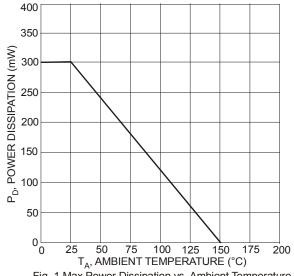
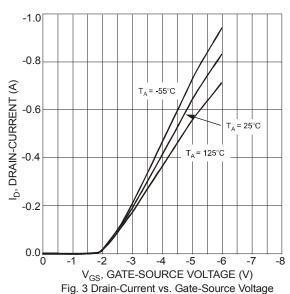
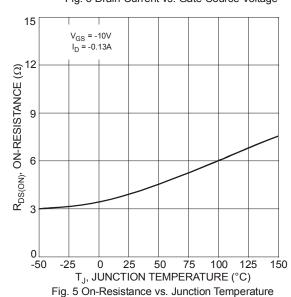


Fig. 1 Max Power Dissipation vs. Ambient Temperature





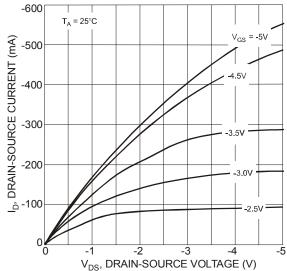
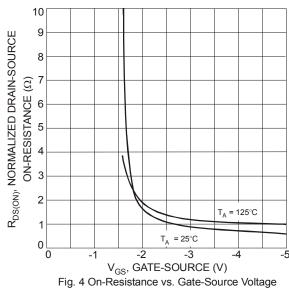


Fig. 2 Drain-Source Current vs. Drain-Source Voltage



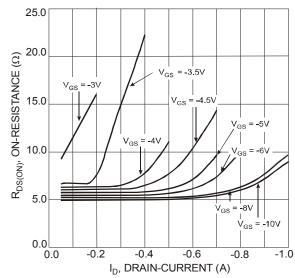
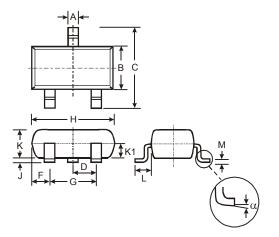


Fig. 6 On-Resistance vs. Drain-Current



Package Outline Dimensions

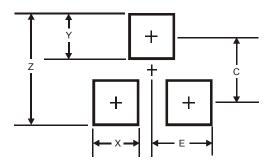
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT23								
Dim	Min	Max	Тур						
Α	0.37	0.51	0.40						
В	1.20	1.40	1.30						
С	2.30	2.50	2.40						
D	0.89	1.03	0.915						
F	0.45	0.60	0.535						
G	1.78	2.05	1.83						
Н	2.80	3.00	2.90						
J	0.013	0.10	0.05						
K	0.903	1.10	1.00						
K1	-	-	0.400						
L	0.45	0.61	0.55						
M	0.085	0.18	0.11						
α	0°	8°	-						
All Dimensions in mm									

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
С	2.0
Е	1.35



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